









PCle	1 x PCle x16 (Single at x16 or dual at x8),
	1 x PCle x8 (shared with dual at x8)
	2 x PCle x4 (1 shared with M.2 Key M)
Mini-PCle	2 x Full/Half size with PCIe x1 and USB 2.0
M.2	$1\times$ M.2 (Key E, 2230) with PCle $\times 1$ and USB 2.0 for Wireless $1\times$ M.2 (Key B, 2280/3042/3052) with PCle $\times 1$ / SATA / USB 3.2 and SIM for 4G / 5G
SIM Socket	2 (1 connected to Mini PCle, 1 connected to M.2 Key B)

Audio

Interface	Realtek ALC897, High Definition Audio.
Ethernet	
Controller/ Speed	4 x I210IT (2 support PoE) + 1 x I219LM (vPro support)
Connector	5 x RJ45
Storage	
M.2	1 x M.2 (Key M, 2230/2242/2280) with PCIe x4 (shared with PCIe x4 slot
	and SATA for SSD
SATA	4 x SATA3 (6Gb/s), support RAID 0/1/5/10
	4 x 2.5" HDD/SSD Tray
CFast	1 x Type II socket (Shared SATA)

Rear I/O

DisplayPort	2
VGA	1
Ethernet	5 x 1 Gigabit LAN
USB	4x USB 3.2 Gen2, 3 x USB 2.0 (1 x internal connector w/lock function)
Audio	1 x Mic-in, 1 x Line-out
COM	6 x COM (2 x RS-232, 4 x RS-232/422/485)
DIO	8-ch DI and 8-ch DO

Watchdog Timer

Output	From Super I/O to drag RESETCON#
Interval	256 Segments, 0, 1, 2,255sec

Power Requirements Input PWR 9V~36V VDC with Ignition control and remote power on/off switch.

	80V Surge Protection, OVP, UVP, OCP and reverse protection	
Environment		

35W CPU: -40°C~75°C (-40°F~167°F)
65W CPU: -40°C~55°C (-40°F~131°F)
80W CPU: -40°C~45°C (-40°F~113°F)
(with FAN inside)
-40°C~85°C (-40°F~185°F)
95% @ 40°C (non-condensing)
95% @ 40°C (non-condensing)
Operating: 50 Grms, half sine 11ms duration (w/ 2.5" SSD/CFast)
Operating: 5 Grms, 5-500 Hz, 3 axes (w/2.5" SSD/CFast)
Operating: 0.3 Grms, 5-500 Hz, 3 axes (w/ HDD)
Contact +/-4kV, Air +/-8kV
EN61000-6-4/-2, CE & FCC Class A
CB, UL

Mechanical

Aluminum heatsink + Metal chassis
Vall Mount
.02mm (W) x 290mm (D) x 209.3mm (H) (7.95" x 11.42" x 8.24")
BD
1

Others

OS Support	Windows 10 & Linux (Ubuntu)
TPM	TPM 2.0



KEY FEATURES

- Intel® 10th Gen (Comet Lake) Xeon® W and Core™ Processors with W480E & Q470E Chipset
- * 4 x 260-pin SO-DIMM up to 128GB (32GB per DIMM)
- $^{\circ}$ 1 x PCle x16 (Gen 3) or 2 x PCle x8 (Gen 3), 2 x PCle x4
- $^{\circ}$ 1 x M.2 Key M, 1 x M.2 Key B, 1 x M.2 Key E, 2 x Mini PCle
- * 4 x USB 3.2 Gen2, 3 x USB 2.0, 6 x COM, 4 x SATA3, 8 x DI, 8 x DO
- * 5 x Intel Gigabit LAN (2 support PoE)
- * Supports Triple Display, 2 x Displayport, 1 x VGA

SPECIFICATIONS

Processor System	iEPF-9000S-EX4	iEPF-9001S-EX4
CPU	Intel® 10 Gen (Comet Lake) Xeon®	W and Core™ Processors
Chipset	Intel®W480E	Intel® Q470E
Socket	LGA 1200	

Memory

Dual Channel DDR4 2933 / 2666 / 2400 / 2133 MHz (ECC memory supported by CPU) - Intel® Xeon® W (10 & 8 Core) and Core™ CPUs support DDR4 up to 2933 MHz - Intel® Xeon® W (6 Core) and Core™ CPUs support DDR4 up to 2666 MHz - Intel Pentium / Celeron CPU support DDR4 up to 2400 MHz - When all 4 x SO-DIMM are occupied, the DDR4 frequency is up to 2133 MHz
128 GB (32 GB per DIMM)
4 x 260-pin SO-DIMM

Graphics

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Controller	Intel® UHD Graphics
DisplayPort	DisplayPort 1.2 , DP++
	Max resolution up to 4096x2160@60Hz
VGA	Max resolution up to 1920x1200@60Hz
MultiDisplay	Triple Display
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